

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	51	((interconnection or wiring or circuit) near (board or substrate) or interposer) near5 (split or gap or divided or partition\$3 or separated or separation or interval) near10 (cte or thermal near expansion or thermally near expand\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 16:48
S2	3325	((interconnection or wiring or circuit) near (board or substrate) or interposer) near3 peripheral	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 16:33
S3	50	((interconnection or wiring or circuit) near (board or substrate) or interposer) near3 peripheral same (cte or thermal\$2 near expan\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 16:45
S4	6	((interconnection or wiring or circuit) near (board or substrate) or interposer) near3 peripheral same (thermal\$2 near mismatch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 16:46
S6	6240	((interconnection or wiring or circuit) near (board or substrate)) near2 (split or gap or divided or partition\$3 or separated or separation or interval)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 16:50
S7	237	((interconnection or wiring or circuit) near (board or substrate)) near5 (split or gap or divided or partition\$3 or separated or separation or interval) same (chip or die or ic) same (solder near ball or solder near bump or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 14:52
S8	152	(substrate or interposer or pcb or pwb or wiring near board or circuit near board) near5 (trench or trenched or groove or grooved) near8 (thermal\$2 near expan\$4 or cte or thermal\$2 near mismatch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 14:48
S9	9	(substrate or interposer or pcb or pwb or wiring near board or circuit near board) near5 (partition\$3) near8 (thermal\$2 near expan\$4 or cte or thermal\$2 near mismatch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 14:52

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S11	266	((interconnection or wiring or circuit) near (board or substrate)) near4 (groove or grooved or trench or trenched) same (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 16:14
S12	1341	((interconnection or wiring or circuit) near (board or substrate)) near6 (ring or annular or annulus or peripheral) same (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 16:14
S13	372	((interconnection or wiring or circuit) near (board or substrate)) near6 (ring or annular or annulus) same (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 16:14
S14	1587	257/E23.004.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 15:32
S15	812	257/E23.004.ccls. and (mounting or substrate or pcb or pwb or board or interposer or base or package) near8 (divided or subdivided or partition\$3 or separated or separation or groove or grooved or trench or trenched or nonintegral or piece or peripheral or exterior or stress or strain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 15:40
S16	680	257/E23.004.ccls. and (stress\$4 or strain\$4 or compress\$4 or tensile or tension)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 15:40
S17	351	257/E23.194.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 12:39
S18	10	("3648131" "4672415" "4951099" "5084750" "5598036" "5635762" "5677564" "5690270" "5744974" "5804771").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/08 10:01
S19	9	("6184570").URPN.	USPAT	OR	ON	2006/03/08 10:02
S20	501	257/E23.181.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 10:42

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S21	243	257/E23.181.ccls. and (stress\$4 or strain\$4 or tensile or tension or compress\$4 or expansion or expanded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 13:41
S22	71	257/683.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 13:41
S23	1311	257/704.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 13:41
S24	588	257/704.ccls. and (stress\$4 or strain\$4 or tensile or tension or compress\$4 or expansion or expanded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:20
S25	3305	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer or package or base) near2 (peripheral or circumferential or periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:23
S26	1014	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near (peripheral or circumferential or periphery)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:26
S27	47	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (segmented or segmenting or divided or separated or interval) near15 (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:35
S28	1	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (partition\$4) near15 (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:47
S29	68	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (partition\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:49

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S30	36	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near8 (peripheral or periphery or circumferential) near8 (central) same (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:52
S31	51	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (ring) same (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:50
S32	53	(heat near sink or cover or lid) near4 (pwb or pcb or wiring near board or wiring near substrate or circuit near board) near4 (solder near ball or ball near grid or bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 16:01
S33	6	(heat near sink or cover or lid) near10 (pwb or pcb or wiring near board or wiring near substrate or circuit near board) near8 (chip or die) and (interposer or stiffener or spacer) near4 (surrounding or around or about or circumscribing or periphery or peripheral) near4 (chip or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 16:08
S34	210	257/704.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 16:27
S35	271	(chip or die) near5 (cap or lid or cover) same (cap or lid or cover) near2 (interconnect\$4 or trace or signal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 16:32
S36	130	(chip or die) near5 (cap or lid or cover) same (cap or lid or cover) near2 (wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 16:33

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S37	14	(US-20020086515-\$ or US-20050078434-\$ or US-20030071353-\$ or US-20040164401-\$ or US-20040150097-\$ or US-20030178719-\$ or US-20010040288-\$).did. or (US-6710457-\$ or US-6653219-\$ or US-6184570-\$ or US-6621161-\$ or US-6720647-\$ or US-6538319-\$).did. or (JP-2000100866-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/03/08 16:35
S38	16	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (subdivided or subdivision)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:42
S39	310	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (slot or slotted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:49
S40	33	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (slot or slotted) same (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:59
S41	283	257/666-798.ccls. and (cavity adj down)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:59
S42	5	("5397921" "5409865" "5646828" "6163458" "6287893").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/09 15:41
S43	26	("5369274" "5440123" "5583377" "5583378" "5620928" "5696666" "5747803" "5768774" "5943212" "5977543" "5986340" "5998241" "5999415" "6020637" "6034427" "6066512" "6103550" "6114760" "6175497" "6184580" "6242279" "6258631" "6323065" "6373131" "6395582" "6403401").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/09 15:47

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S44	18	("5240588" "5397921" "5420460" "5455456" "5583378" "5633533" "5640047" "5663530" "5710459" "5739581" "5832596" "5844168" "5972736" "5976916" "5998241" "6066512" "6248612" "6258631"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/09 15:47
S45	63	("6020637").URPN.	USPAT	OR	ON	2006/03/09 16:46
S46	82	interposer near3 (ring or peripheral or surrounding or around or enclosing or ringing or (chip or die) near2 (cavity or aperture or opening)) and (heat or thermal) near (sink or sinking or spreader or spreading) and (bga or ball near grid or solder near ball or solder near bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:49
S47	20	(US-20050078434-\$ or US-20010040288-\$ or US-20040150097-\$ or US-20020086515-\$ or US-20040164401-\$ or US-20030178719-\$ or US-20030071353-\$ or US-20050035452-\$ or US-20030174478-\$ or US-20030146508-\$ or US-20030080423-\$ or US-20020050407-\$).did. or (US-6621161-\$ or US-6184570-\$ or US-6710457-\$ or US-6653219-\$ or US-6720647-\$ or US-6538319-\$ or US-6650015-\$).did. or (JP-2000100866-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/03/09 17:21